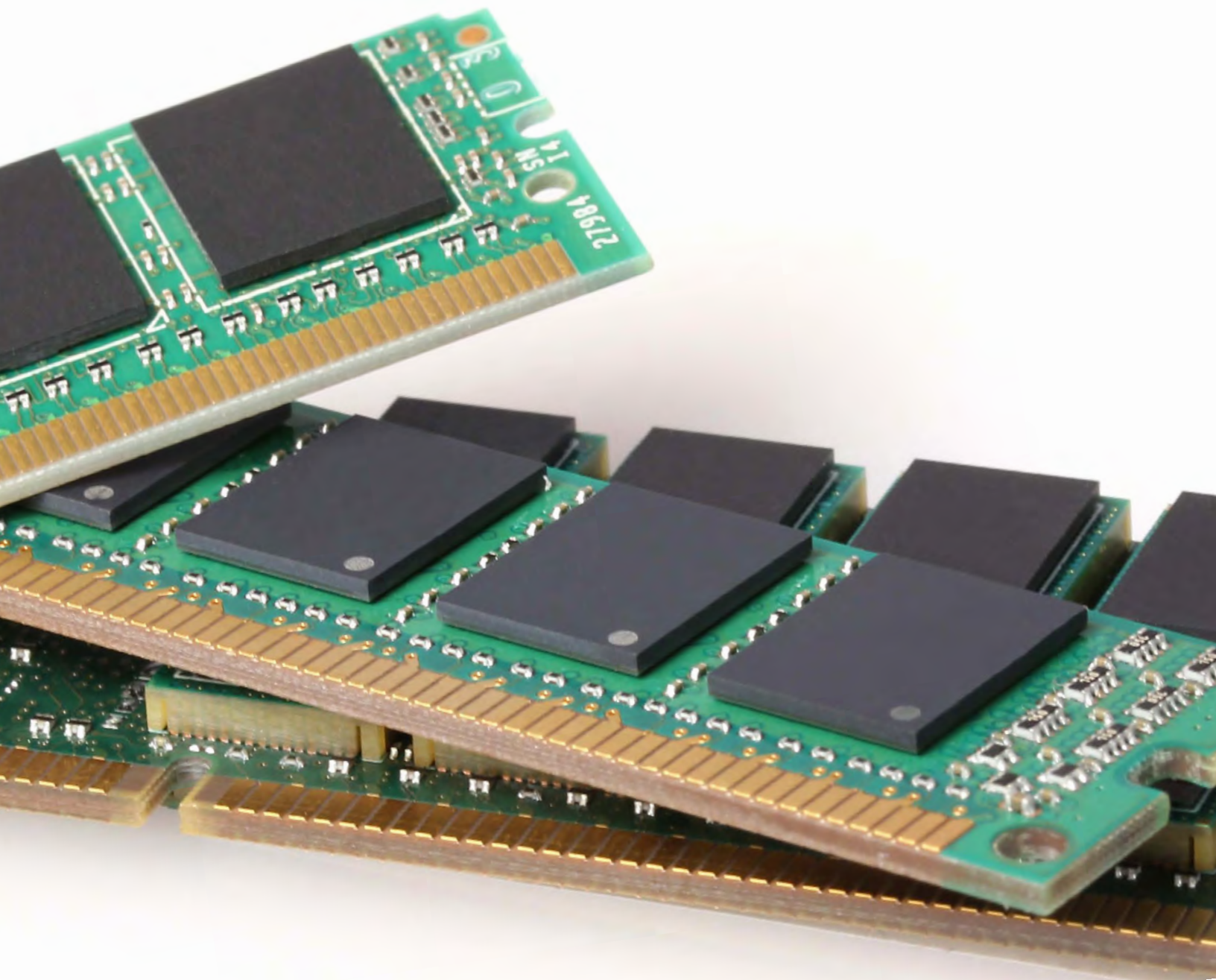


DRAM Product Portfolio

High performance DRAM technology for enterprise, embedded, and network infrastructure

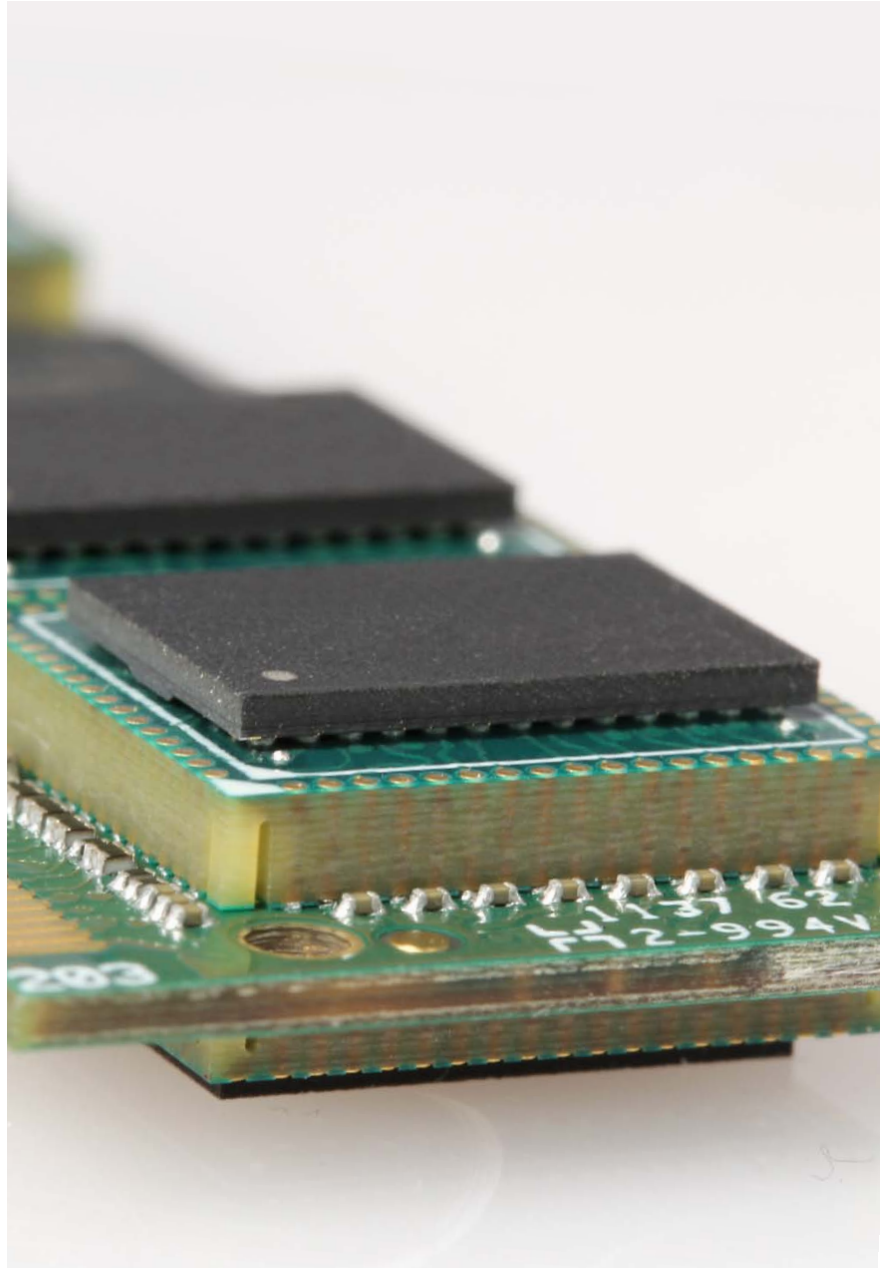
ArxCis-NV | DDR3 | DDR2 | DDR1 | DRAM Stacking | Legacy DRAM



DRAM STACKING

High Density DRAM Stacking Technology

Form Factor	Technology	Speed	Densities
LR-DIMM	DDR3	up to 1600 MT/s	32GB
RDIMM	DDR3	up to 1600 MT/s	32GB
VLP RDIMM	DDR3	up to 1600 MT/s	16GB
VLP Mini RDIMM	DDR3	up to 1600 MT/s	8GB
VLP SORDIMM	DDR3	up to 1600 MT/s	8GB
VLP RDIMM	DDR2	up to 800 MT/s	4GB
VLP MiniRDIMM	DDR2	up to 800 MT/s	4GB
VLP RDIMM	DDR	up to 400 MT/s	2GB



BGA Stacking Technology

Designing the highest density memory module solutions typically requires multi-die packaged DRAM (DDP or QDP). These multi-die packaged DRAMs have significant cost premiums, due to compound yield loss at test. Viking Technology's DRAM stacking approach, enables the most cost effective solution in the industry. Supporting high capacity DIMMs for servers and also small form factor solutions for telecommunication and embedded markets, Viking's DRAM stacking technology is the solution for our OEM customers' high density DRAM module needs.

ARXCIS-NV

DDR3 NVDIMM

Persistent Memory

Battery Free

10 Years Data Retention

Zero Recurring Costs

Storage Class Solution

DDR3 DIMM Integration

100% Data Security

Up to 16GB SSD

NVDIMM



ArxCis-NV™ : Non-Volatile Memory Technology

The ArxCis-NV™ is a DDR3 Non-Volatile DIMM, which delivers both performance and reliability to enterprise applications. This non-volatile memory module has been designed to be integrated into industry standard x86 servers via DDR3 DIMM sockets. Designed to preserve critical data in the event of a power or system failure, the ArxCis-NV™ module replaces both battery backed up (BBU) DIMMs and RAID cards. ArxCis-NV™ enables the host system to recover from a failure event with simplicity and ease.

DRAM MODULE FAMILY

Form Factor of Products



RDIMM



Mini RDIMM



UDIMM



Mini UDIMM



VLP RDIMM



VLP Mini RDIMM



VLP UDIMM



VLP Mini UDIMM



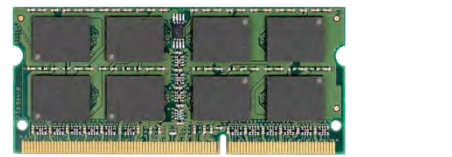
Stacked LRDIMM



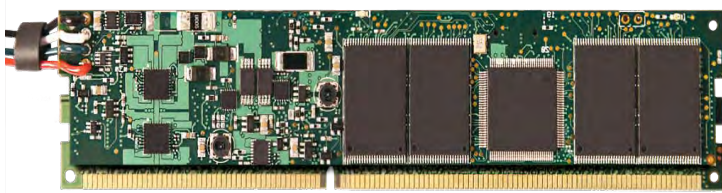
SORDIMM



Stacked VLP RDIMM



SODIMM



ArxCis-NV-DIMM



SOUDIMM

DRAM OVERVIEW

DDR3, DDR2, and DDR1

Broadest DRAM Offering

JEDEC Standard

RoHS Certified

Customized Testing

Bill of Materials (BOM)

Extending Burn-in Testing

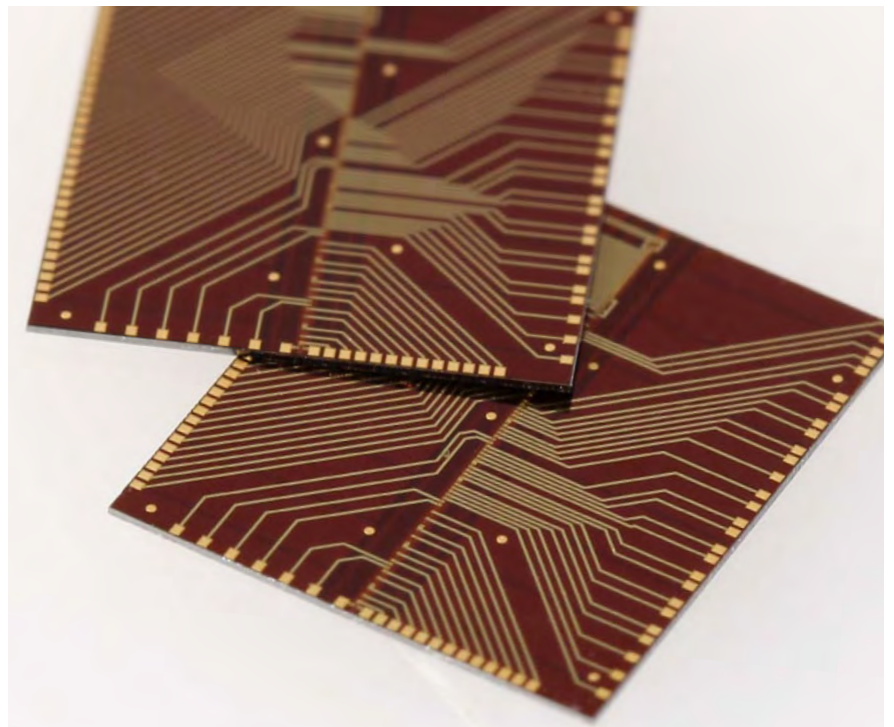
Thermal Modeling

Small Form Factors

Form Factor	DDR3	DDR2	DDR1
LRDIMM	up to 32GB		
RDIMM	up to 32GB	up to 16GB	up to 4GB
UDIMM	up to 8GB	up to 8GB	up to 2GB
MiniRDIMM	up to 8GB	up to 8GB	up to 1GB
MiniUDIMM	up to 8GB	up to 4GB	up to 1GB
VLP MiniRDIMM	up to 8GB	up to 4GB	
VLP MiniUDIMM	up to 8GB	up to 4GB	
VLP RDIMM	up to 16GB	up to 8GB	up to 4GB
VLP UDIMM	up to 8GB	up to 4GB	up to 1GB
VLP SORDIMM	up to 8GB		
SODIMM	up to 8GB	up to 4GB	up to 1GB
SORDIMM	up to 8GB	up to 4GB	up to 1GB
SOUDIMM	up to 8GB	up to 4GB	up to 1GB
SOCDIMM		up to 4GB	up to 1GB
ULP RDIMM	up to 16GB	up to 8GB	
ULP MiniRDIMM	up to 8GB		
ULP MiniUDIMM	up to 8GB		

DRAM Technology

From enterprise to embedded to network infrastructure, OEMs from around the world trust in Viking Technology's DRAM modules and technology. Viking has more than just a long history of supporting OEMs with edging lead DRAM technology but also provides its customers with legacy support. With the industry's broadest offering of standard DRAM modules, specialty modules, and small form factor modules, Viking is not only a provider of high-quality memory but a partner in DRAM technology.



Viking Technology has over two decades of experience supporting Original Equipment Manufacturers (OEMs) with the industry's most comprehensive range of DRAM modules. Leveraging advanced packaging expertise, locked BOM control, and AS9100, TL 9000, and ISO 14001 certified facilities, Viking Technology is able to deliver the highest quality DRAM modules that meet the requirements of the Enterprise, Telecommunications and Embedded markets.

As a memory partner, Viking Technology prides itself on supporting legacy technology to meet the demands of specific market segments. Viking Technology support it's OEMs with DDR1, SDRAM, RAMBUS and other legacy solutions while maintaining the highest quality levels, locked Bill of Materials (BOMs), extended temperature testing, and supporting the highest density modules in the market today.



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